

## ICMC Technical Editors

**U. (Balu) Balachandran***Chief Technical Editor*

University of Colorado-Boulder

Dept. of Mechanical Engineering

Boulder, Colorado, USA

Email: Uthamalingam.Balachandran@colorado.edu

**Shreyas Balachandran**

College of Engineering, FAMU-FSU

Tallahassee, Florida, USA

Email: sbalachandran@fsu.edu

**Lance Cooley**

ASC / NHMFL - Florida State University

Tallahassee, Florida, USA

Email: ldcooley@asc.magnet.fsu.edu

**Pashupati Dhakal**

Thomas Jefferson National Accelerator Facility

Newport News, Virginia, USA

Email: dhakal@jlab.org

**Karl T. Hartwig**

Texas A&amp;M University

Materials Science and Engineering Department

College Station, Texas, USA

Email: thartwig@tamu.edu

**Timothy Haugan**

U.S. Air Force Research Laboratory

Beavercreek, Ohio, USA

Email: timothy.haugan@us.af.mil

**Eric Hellstrom**

ASC / NHMFL – Florida State University

Tallahassee, Florida, USA

Email: hellstrom@asc.magnet.fsu.edu

**Takanobu Kiss**

Kyushu University

Fukuoka, Japan

Email: kiss@sc.kyushu-u.ac.jp

**Chris Kovacs**

Scintillating Solutions LLC

Columbus, Ohio, USA

Email: ckovacs@scintsol.com

**Sastry Pamidi**

FAMU-FSU College of Engineering

Center for Advanced Power Systems

Tallahassee, Florida, USA

Email: pamidi@eng.famu.fsu.edu

**Ernst Wolfgang Stautner**

GE HealthCare – Technology &amp; Innovation

Center (HTIC)

Niskayuna, New York, USA

Email:

ErnstWolfgang.Stautner@gehealthcare.com

**Michael Sumption**

The Ohio State University

Columbus, Ohio, USA

Email: sumption.3@osu.edu

**Editorial Management**

Centennial Conferences | 908 Main Street, Suite 350 | Louisville, CO 80027 USA

Email: cecimc@centennialconferences.com

